



## [WeE2] AI-Driven CMP and Emerging Process Strategies

<b>Session Date</b>	November 12 (Wed.), 2025
<b>Session Time</b>	14:10-15:40
<b>Session Room</b>	Room E (Sicily Room, 1F)
<b>Session Chair</b>	Prof. Seho Sun (Yeungnam Univ., Korea)

### [WeE2-1] [Invited]

14:10-14:40

#### Machine Learning-Based Strategic Corrosion Management for Targeted Inhibitor Implementation in CMP Applications

Jihoon Seo (Clarkson Univ., USA)

### [WeE2-2]

14:40-15:00

#### Mechanism on Formation of Selective Hindrance Layer on Si-Film Enhancing Etch-Rate Selectivity of Si<sub>1-x</sub>Gex- to Si-Film

Chang-Jin Lee and Jea-Gun Park (Hanyang Univ., Korea)

### [WeE2-3]

15:00-15:20

#### Design Rules for Micro-Structured Chemical Mechanical Polishing Pads to Enhance MRR

Hyun Jun Ryu, Seounghee Yun, and Sanha Kim (KAIST, Korea)

### [WeE2-4] [Invited]

15:20-15:40

#### CMP: Enabling Advanced Packaging for the AI Era

Nandan Baradanahalli Kenchappa, Taketo Sekine, Swetha Barkam, Christopher Lai, Jianshe Tang, and Asheesh Jain (Applied Materials, USA)